

SOT1079-1

plastic low profile fine-pitch ball grid array package; 141 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFPGA141
Package type industry code	LFPGA141
Package style descriptive code	LFPGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	10-4-2008

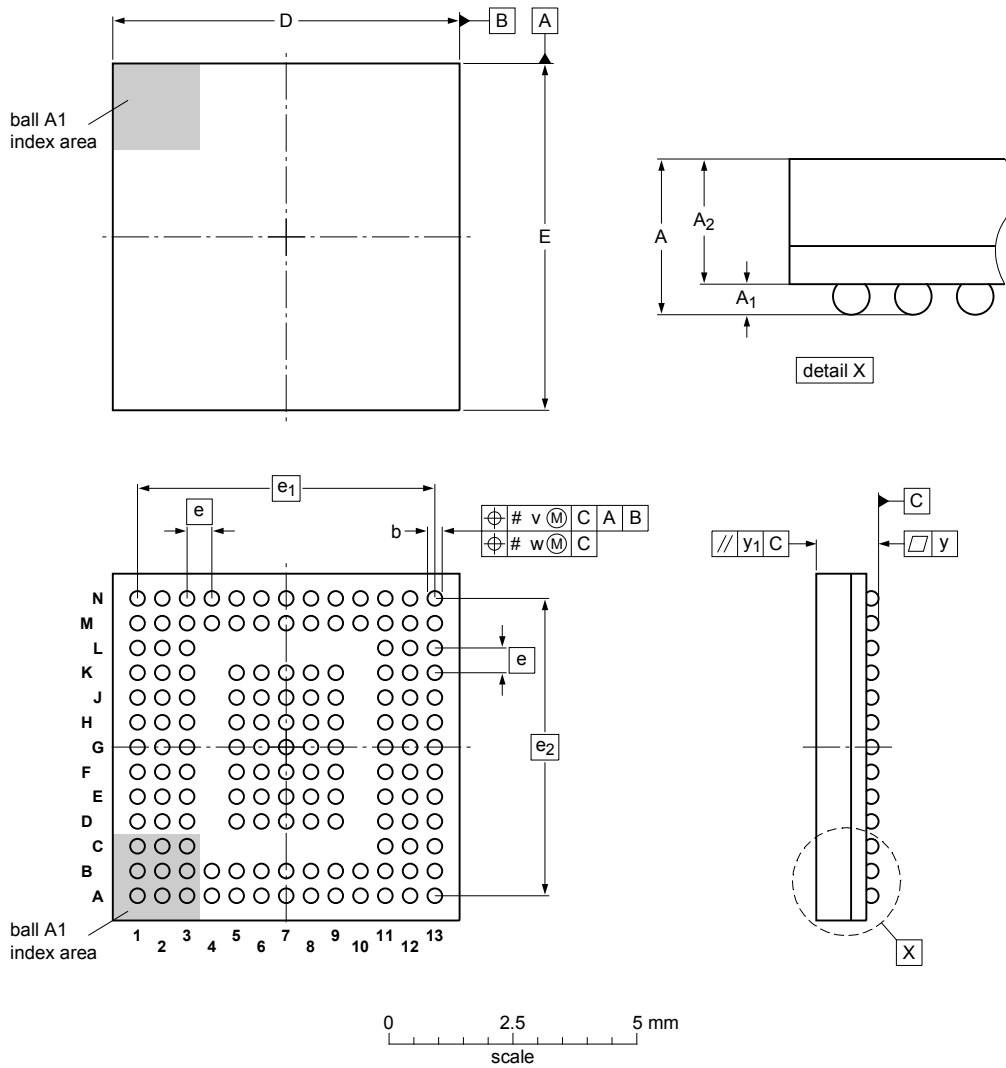
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	1.15	-	1.26	1.4	mm
A ₂	package height	0.95	-	1.01	1.1	mm
n ₂	actual quantity of termination	-	-	141	-	



2. Package outline

LFBGA141: plastic low profile fine-pitch ball grid array package; 141 balls SOT1079-1



DIMENSIONS (mm are the original dimensions)

UNIT		A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	max	1.40	0.30	1.10	0.35	7.1	7.1	0.5	6	6	0.15	0.05	0.08	0.1
	nom	1.26	0.25	1.01	0.30	7.0	7.0							
	min	1.15	0.20	0.95	0.25	6.9	6.9							

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1079-1		---	---			08-03-19 08-04-10

Fig. 1. Package outline LFBGA141 (SOT1079-1)

3. Soldering

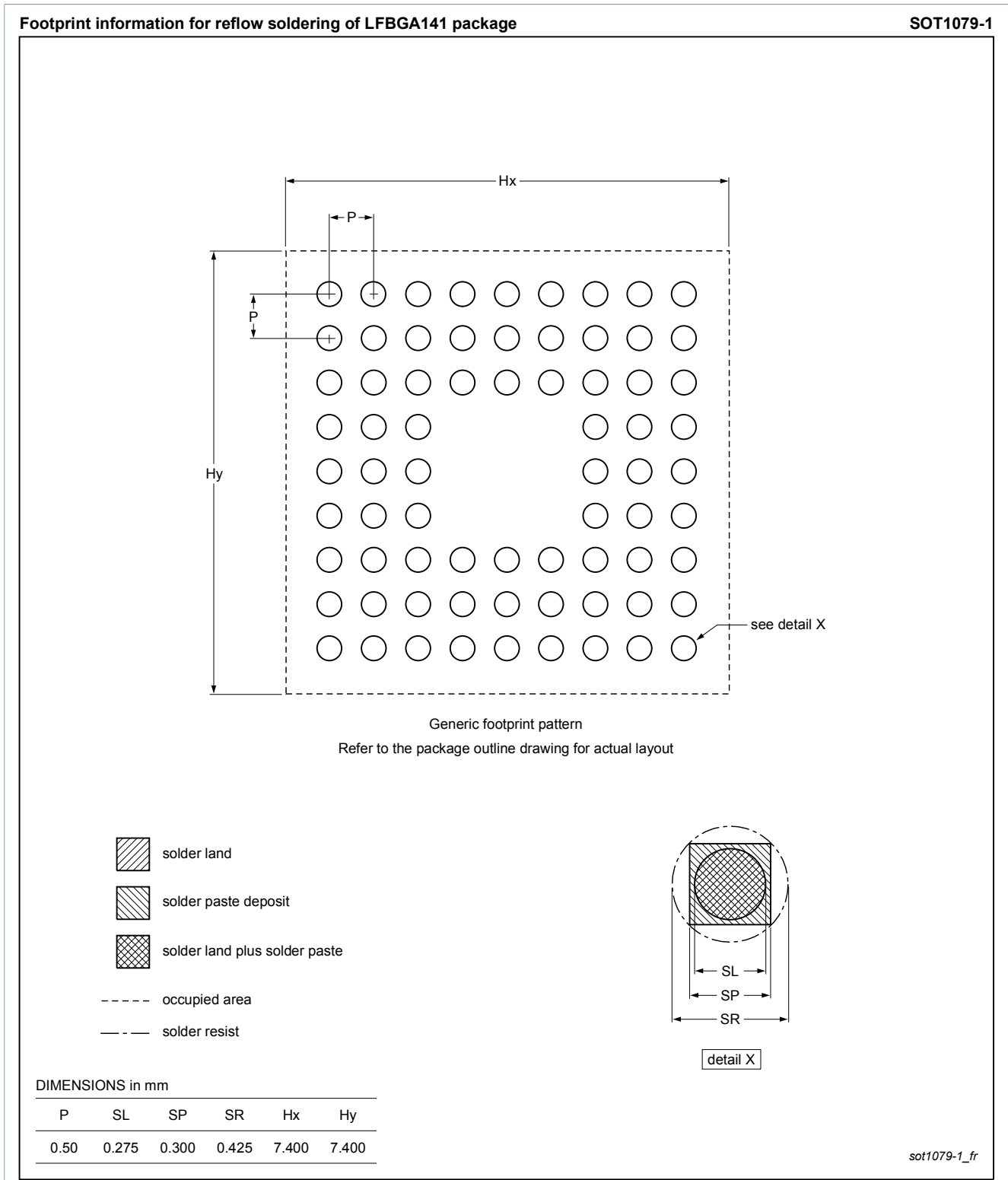


Fig. 2. Reflow soldering footprint for LFBGA141 (SOT1079-1)

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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